

ASM Pacific Technology Limited

(STOCK CODE 股份代號 00522)

2005 ANNUAL REPORT AND ACCOUNTS 年報



30

YEARS
of
INNOVATION

三十年高科技拓新

30

*years of innovation
has led to ASM becoming the
world's leading semiconductor
assembly and packaging
equipment company*

三十年之拓新使
ASM 於全球半導體
裝嵌及包裝設備
行業稱冠

Market Capitalization as of Mid Year (US\$ Million)
年中市值 (百萬美元)



30 Years of Innovation

三十年高科技拓新

1975

With US\$5,000 initial capital investment and as a manufacturer representative of molding compound and encapsulation mold, ASM was co-founded by the present chairman, Arthur H. del Prado and the present managing director, Patrick Lam as a wholly owned subsidiary of Dutch company ASM International.

ASM於1975年為本公司現任董事會主席 Arthur H. del Prado先生及現任董事總經理林師龐先生以五千萬美元資本共同創立，為荷蘭ASM International之全資附屬公司，代理封裝模具及塑料。



1981

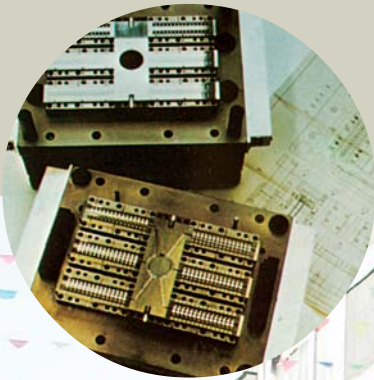
ASM Assembly Materials Ltd (AAM) was acquired and after company restructuring, an automated leadframe stamping and plating factory was established.

ASM收購先進半導體物料科技有限公司，重組後成為自動化生產沖壓及電鍍之引線框架工廠。

1980

ASM Assembly Automation Ltd. (AAA), involved in manual wire bonder manufacturing, was acquired and reorganised with new key management and strengthened R&D functions.

ASM收購先進自動器材有限公司(手動焊線機製造廠)，重新改組主要管理層及加強研究及發展工作。





1988

ASM was listed on the Hong Kong Stock Exchange with an initial market capitalization of US\$75 million. The Group's automatic die bonder, model AD809, was awarded "The Federation of Hong Kong Industries Award for Good Design in Machinery and Equipment for Improving Manufacturing Process Category" in the 1988 Governor's awards for Hong Kong design competition organised by The Hong Kong Federation of Industries.

1988年底ASM於香港聯交所上市，當時市值達七千五百萬美元。集團之自動管芯焊接機AD809參加香港工業總會舉辦之香港總督設計比賽，榮獲「香港工業總會優異設計獎(改良生產工序機械設備類)」。

1989

ASM Precision Machinery Manufacturing Ltd was established in Shenzhen, China for the fabrication of metal parts and subassemblies. An enlarged leadframe factory in Hong Kong with newly equipped clean room facilities came on stream towards the end of the year.

於中國深圳成立深圳先進精密機械製造廠，製造金屬零件及組裝。於年終時更擴充香港引線框架廠房，增加「潔淨室」生產設備。



1990

ASM Technology Singapore Pte Ltd was established as the second ASM R&D and business centre, facilitating ASM's market coverage in the southern region.

Preparation for our own ASM building commenced and production of our new AB309 gold wire bonder was relocated to Singapore. The success of our China venture prompted our expansion in Shatoujiao, Shenzhen.

ASM Technology Singapore Pte Ltd. 為ASM第二個研究及發展和業務中心，有助涵蓋ASM在亞洲南部之銷售市場。同時著手自建廠房，生產剛移師至新加坡的新產品AB309自動金線焊線機。同年，ASM在中國運作的成功更加速深圳沙頭角廠房的擴展。

30 Years of Innovation

三十年高科技拓新

1997

The stunning technological success of the gold wire bonder AB339 with 50 micron pad-pitch capability, puts ASM among the world's top three assembly equipment suppliers. Market acceptance of the ASM IDEALine provides a factory automation solution needed by the industry.

AB339金線焊線機(具50微米線距功能)獲得空前成功，令ASM成功躋身全球裝嵌設備業之首三名行列。同時推出之ASM IDEALine為業內提供所需生產自動化方案，廣為市場接受。



2002

ASM rose to become the world leader in the Semiconductor Assembly and Packaging Equipment Industry and is known for its process innovation, packaging development, factory automation, and total solution marketing strategies.

ASM成為全球半導體裝嵌及包裝設備業第一位，並以其技術創新、包裝研發、生產自動化及全方位解決方案等成功市場策略廣為知悉。

2000

With its record turnover ASM became the world's second largest semiconductor assembly equipment manufacturer.

以其創紀錄的銷售額，ASM躍升為全球第二大之半導體裝嵌設備製造商。





2003

ASM expands its factory operations in China occupying over 70,000 square metres of floor space, including a new stamped leadframe plant in Fu Yong, Shenzhen.

ASM擴展其在中國之生產能力，廠房面積達七萬平方米，包括在深圳福永之一間全新沖壓引線框架廠。

2004

Finance Asia Magazine voted ASM as one of the ten best managed companies in Asia.

ASM獲 *Finance Asia* 雜誌評選為十佳亞洲管理公司之一。

2005

ASM completes construction of its new 280,000 square feet Malaysian factory equipped with new strip plating lines for her etched leadframe production.

ASM完成建於馬來西亞之廿八萬平方呎新廠房，並添置新生產線以提升其蝕片引線框架產能。

